

(54) RESIST REMOVING APPARATUS

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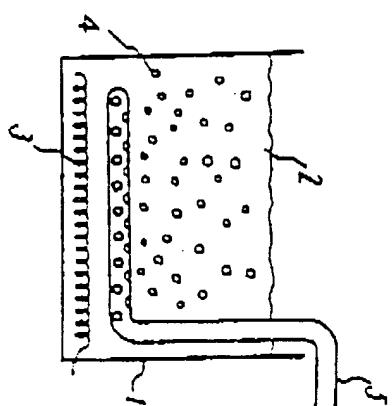
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(21) APPENDIX B
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PURPOSE: To prevent decrease of concentration of hydrogen peroxide solution and to enable resist to be removed stably, by dissolving ozon gas in a heated mixture of sulfuric acid and the hydrogen peroxide solution.

CONSTITUTION: Liquid mixture 2 consisting of concentrated sulfuric acid and hydrogen peroxide in proportions of about 4:1 is introduced into a chemical vessel 1 and heated by a heater 3 to a temperature of 100~130°C. Then, ozon gas 4 is fed into the liquid from a bubbler 5. Bubbles of the ozon gas produced thereby are contacted with the heated liquid mixture 2 of the concentrated sulfuric acid and hydrogen peroxide, and a part of the ozon gas is dissolved in the solution. A wafer having resist thereon is dipped in the solution for about 15 minutes, whereby the resist is removed from the wafer. The resist removing solution may be substituted by a mixture of concentrated sulfuric acid and concentrated nitric acid. According to this method, deterioration of capability of removing the resist can be prevented effectively.



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